



Product Change Notification / JAON-17DZYV010

Date:

19-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4560 Initial Notice: Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.

Affected CPNs:

[JAON-17DZYV010_Affected_CPN_02192021.pdf](#)

[JAON-17DZYV010_Affected_CPN_02192021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of SIGN as a new assembly site for selected SST39LF80xx, SST39VF160xx and SST39VF80xx device families available in 48L TSOP (12x20mm) package.

Pre Change:

Assembled at LPI using lead frame with paddle size 207x142mils (applicable for SST39VF160xx device family) and using lead frame with paddle size 160x130mils (applicable for SST39LF80xx and SST39VF80xx device families)

Post Change:

Assembled at SIGN using lead frame with paddle size 209x165mils (applicable for SST39VF160xx device family) and using

lead frame with paddle size 159x165mils (applicable for SST39LF80xx and SST39VF80xx device families)

Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	Lingsen Precision Industries, LTD. (LPI)		Signetics Corporation (SIGN)	
Bond Wire material	Au		Au	
Die Attach material	8340		8340	
Mold compound material	G700		G700	
Lead frame material	C7025		C7025	
DAP Surface plating	Ring plating		Double ring plating	
Lead frame paddle size	207x142mils Note 1	160x130mils Note 2	209x165mils Note 1	159x165mils Note 2
	See attached pre and post change comparison			

Note 1: Applicable for SST39VF160xx device family.

Note 2: Applicable for SST39LF80xx and SST39VF80xx device families

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying SIGN as a new assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:August 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2021					-->	August 2021				
Workweek	06	07	08	09	10		32	33	34	35	36
Initial PCN Issue Date			X								
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 19, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-17DZYV010_Qual_Plan.pdf](#)

[PCN_JAON-17DZYV010_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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